

Full Material Declaration for attached parts list

Report generated: 26 January 2026, 15:05 GMT



Diotec Semiconductor AG

DUNS number: 330866844

-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany

Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved on 26 January 2026, 15:04 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.69%	SILVER, ELEMENTAL	7440-22-4	13.8%
			Silicon	7440-21-3	86.2%
Die attach	Lead and Lead alloys	0.93%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead	7439-92-1	92.5%
			EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements		
Encapsulation	EP (Epoxy resin)	61.55%	Carbon black	1333-86-4	1%
			Magnesium hydroxide (Mg(OH) ₂)	1309-42-8	2%
			Phenol, polymer with formaldehyde	9003-35-4	12%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	20%
			Quartz	14808-60-7	65%
			Exempt from other regulatory requirements		
Leadfinish	Tin plating	1.48%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	34.35%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-214AA/SMB_(JY)_H-free	Diode SMD	0.09765	g